

ABSTRACT

A semiconductor device includes a first layer, a plurality of first test elements which are arranged in the first layer, a second layer which is different from the first layer and has a first surface and a second surface opposed to the first surface, the first surface of the second layer being adhered to the first layer, an opening portion which is arranged on the second surface of the second layer, and a plurality of pads which are arranged in the second layer and are electrically connected to the first test elements, a part of the pads being exposed from the opening portion.